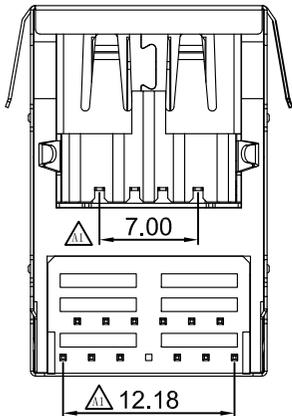
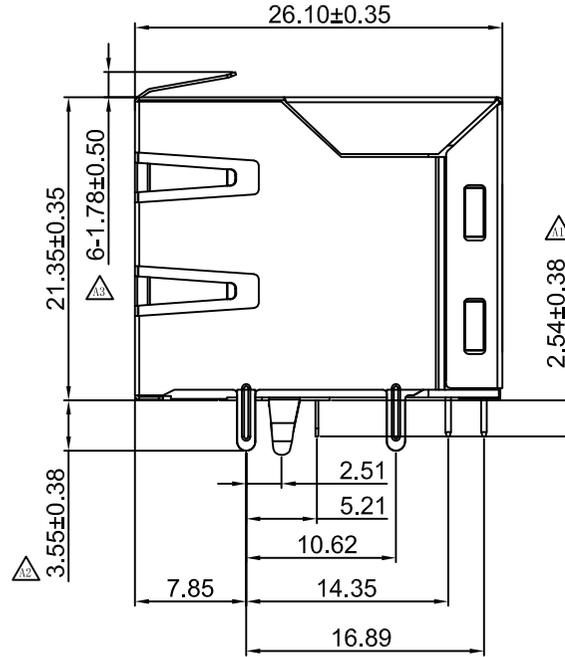
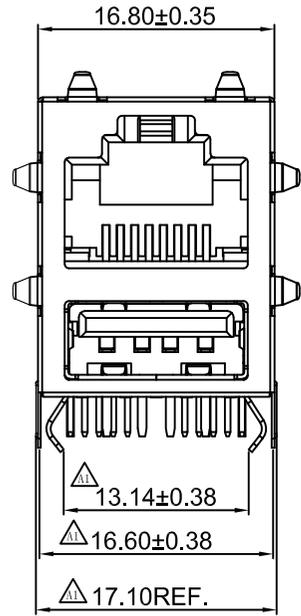


GP Component

1. MECHANICAL DIMENSIONS:



NOTES:

1. MATERIAL & FINISH

RJ45:

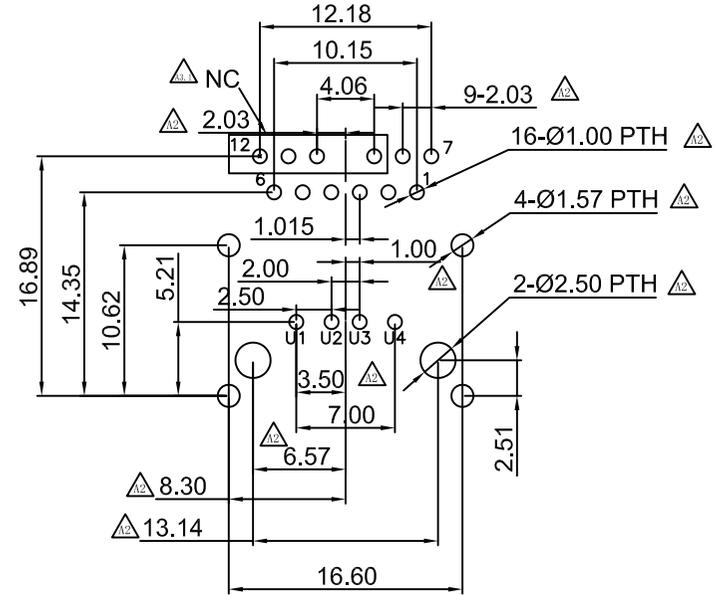
HOUSING: PBT, UL94V-O BLACK.
 CONTACTS: PHOSPHOR BRONZE,
 CONTACT AREA 6u", TIN PLATING ON.
 SOLDER TAILS, NICKEL PLATED OVERALL.
 SHELL: COPPER ALLOY, NICKEL PLATED OVERALL.

USB 2.0:

HOUSING: PBT, UL94V-O BLACK.
 CONTACTS: COPPER ALLOY, GOLD FLASH ON.
 CONTACT AREA, TIN PLATING ON SOLDER.
 TAILS, 50u" MIN. NICKEL PLATED OVERALL.
 SHELL: COPPER ALLOY, NICKEL PLATED OVERALL.

2. RJ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

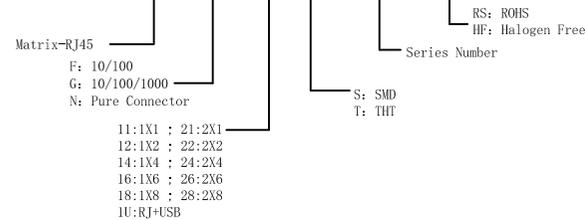
REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A1			Modify Size & tolerance & Note	2025/03/04	Vince
A2			Modify PCB LAYOUT Size	2025/03/06	Vince
A3			Add Size & Electrical Specification	2025/03/13	Vince
A3.1			Add Pcb Layout Annotation	2025/03/21	Vince



Suggested PCB Layout (Top View)
 (Tolerance: ±0.05)

MATRIX PART NO:

MRJ N-1U T 1973 RS



USB 2.0 CONTACT PINS	
Pin NUMBER	SIGNAL NAME
U1	VBUS
U2	D-
U3	D+
U4	GND
Shell	Shield



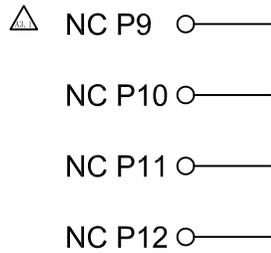
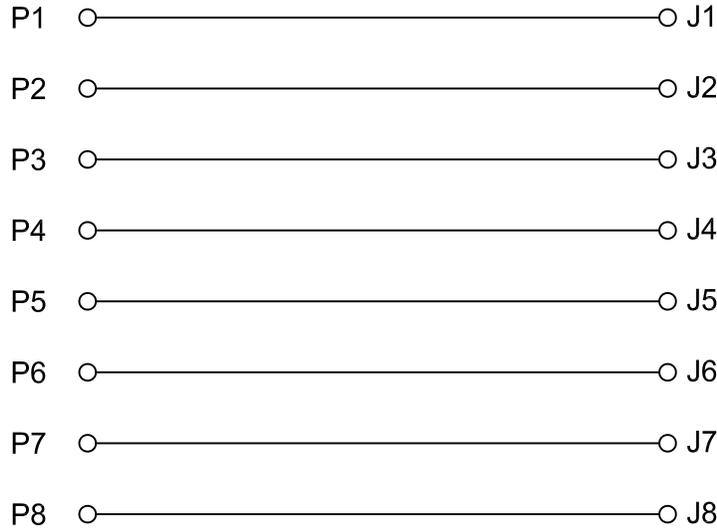
Matrix Electronics Co., Ltd

TOLERANCE:		DESIGN BY :	DATE :	PART NAME:	
X		Vince Chen	2025/03/21	RJ45+USB2.0 CONN, W/O LED	
X.X	±0.38	CHECKED BY:	DATE :	PART NO.	MRJN-1UT1973RS
X.XX	±0.25	Hanson Huang	2025/03/21	MOLD NO.	NA
X.XXX	±0.13	APPROVED BY1:	DATE :	DRAW NO.	
X° ±2°		Richard Hsieh	2025/03/21	SHEET NO.	1 OF 2
UNIT: mm [inch]		APPROVED BY2:	DATE :		
SCALE:1:1	SIZE:A4	Richard Hsieh	2025/03/21		

GP Component

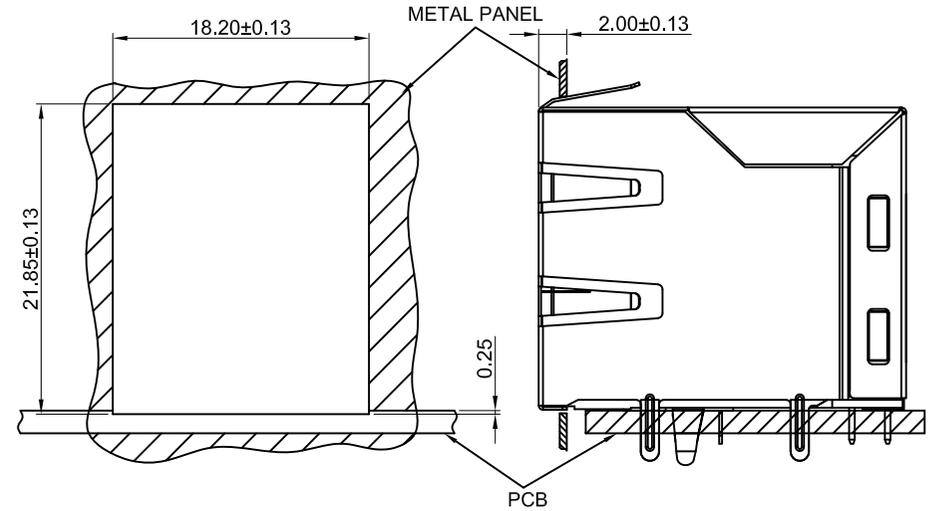
2.SCHEMATIC

SCHEMATIC



REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A1			Modify Size & tolerance & Note	2025/03/04	Vince
A2			Modify PCB LAYOUT Size	2025/03/06	Vince
A3			Add Size & Electrical Specification	2025/03/13	Vince
A3.1			Add Peb Layout Annotation	2025/03/21	Vince

- △ 3.Electrical Specification @25°C:
 - 3.1 Voltage rating:125V AC.
 - 3.2 Current rating:1.5AMP.
 - 3.3 Insulation resistance: 500 MΩ minimum initial after 500V DC for 1minute.
 - 3.4 Low level Contact resistance:
 - Single terminal 20 mΩ Max initial
 - 40 mΩ maximum after durability test.
 - 3.5 Hi-Pot Test: Between adjacent pins 1000VDC/1mA/60sec.
- 4.Operating and Storage Temperature:
 - △ 4.1 Operating Temperature : -40°C to +85°C.
 - 4.2 Storage Temperature : -40°C to +85°C.
- 5.Wave soldering peak temperature:260°C.



Matrix Electronics Co., Ltd

TOLERANCE: X X.X ±0.38 X.XX ±0.25 X.XXX ±0.13 X° ±2°	DESIGN BY : Vince Chen	DATE : 2025/03/21	PART NAME: RJ45+USB2.0 CONN, W/O LED	
	CHECKED BY: Hanson Huang	DATE : 2025/03/21	PART NO.	MRJN-1UT1973RS
 UNIT: mm [inch] SCALE:1:1 SIZE:A4	APPROVED BY1: Richard Hsieh	DATE : 2025/03/21	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2025/03/21	DRAW NO.	
			SHEET NO.	2 OF 2